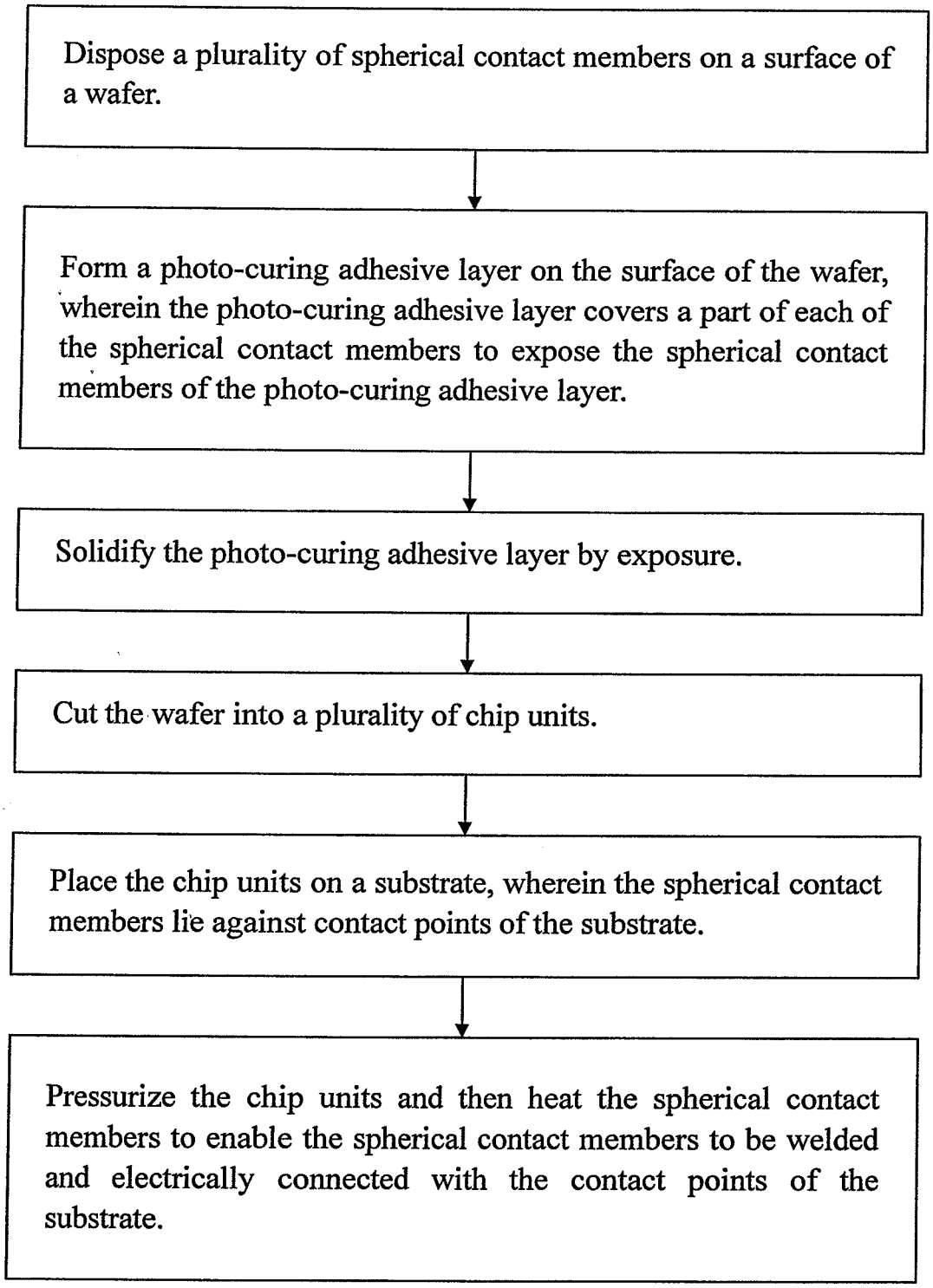

Dispose a plurality of spherical contact members on a surface of a wafer.
Form a photo-curing adhesive layer on the surface of the wafer, wherein the photo-curing adhesive layer covers a part of each of the spherical contact members to expose the spherical contact members of the photo-curing adhesive layer.
Solidify the photo-curing adhesive layer by exposure.
Cut the wafer into a plurality of chip units.
Place the chip units on a substrate, wherein the spherical contact members lie against contact points of the substrate.
Pressurize the chip units and then heat the spherical contact members to enable the spherical contact members to be welded and electrically connected with the contact points of the substrate.

FIG .1

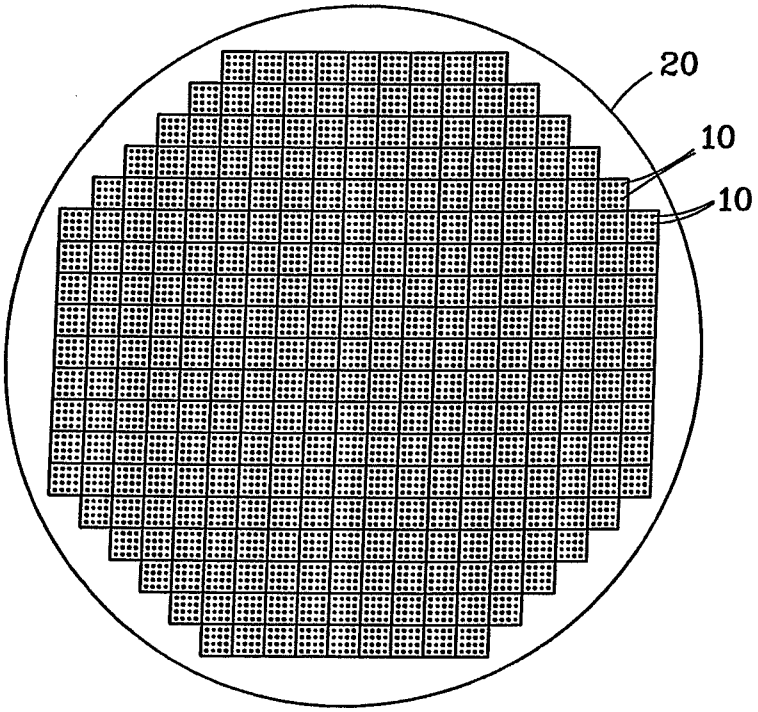


FIG. 2

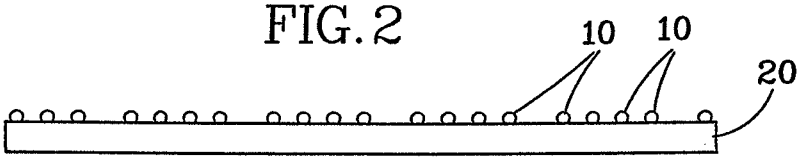


FIG. 3

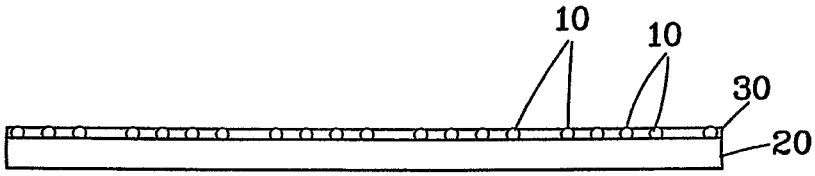


FIG. 4

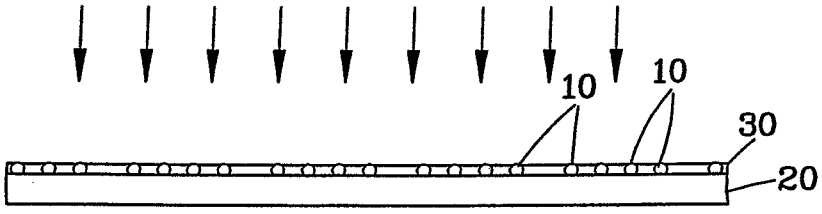


FIG. 5

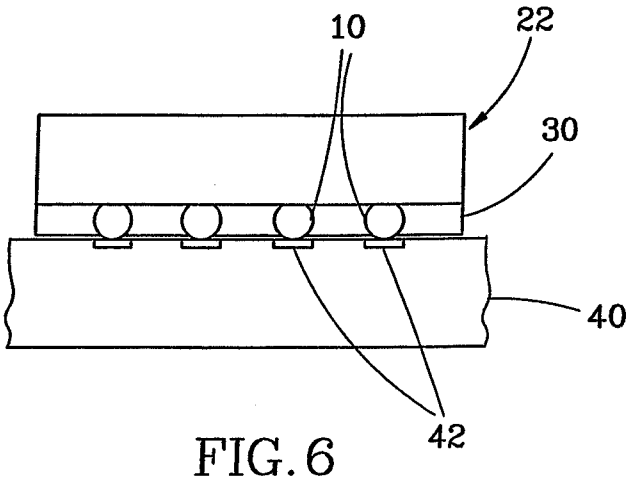


FIG. 6

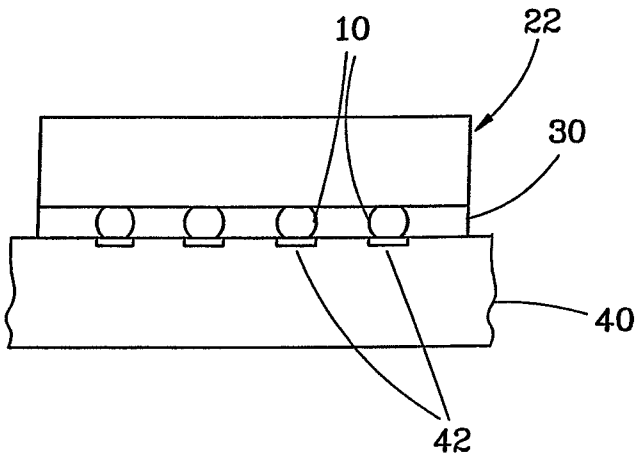


FIG. 7

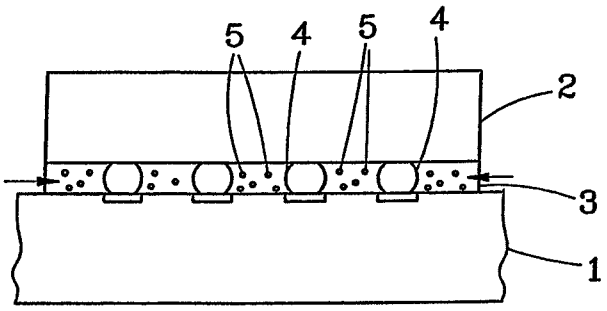


FIG. 8
PRIOR ART